dinema S.p.A. ELECTRONICS	TECHNOLOGY PROFILE

GENERAL INFO
RoHS and NON RoHS capability
SMT and THT areas under temperature and humidity control
ElectroStatic and Moisture Sensitivity Management

MANUFACTURING CAPACITY - SMT ASSEMBLY	
MAX. ASSEMBLY CAPABILITY	300 milion of components per year
MIN. COMPONENT DIMENSION	01005, BGA, LGA, QFN fine-pitch (0,2 mm)
MAX. COMPONENT DIMENSION	150 mm x 50 mm
MAX. BOARD DIMENSION	410 mm x 360 mm
SOLDERING	nitrogen atmosphere

MANUFACTURING CAPACITY - THT ASSEMBLY	
COMPONENTS PREPARATION	automatic / semi-automatic
MAX. BOARD DIMENSION	370 mm x 450 mm
SOLDERING	single or double wave and selective, nitrogen atmosphere

PROCESS CONTROL	
AOI INSPECTION	100%, solder joints and components placement
X-RAY INSPECTION	for BGA and non-visible characteristics

TESTING, AGEING, SAFETY	
ICT FLYING PROBES	with power-on features
ICT BED OF NAILS	with power-on and integrated programming functionalities
AUTOMATIC FUNCTIONAL	with National LabView®-based platforms
SEMI-AUTOMATIC FUNCTIONAL	with customized simulation tools
AGEING	burn-in and run-in climatic chambers
SAFETY	hi-voltage, insulation, ground protection, leakage current